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## Product Preview

# **CAN Micro-Stepping Motor Driver**

#### Introduction

The AMIS-30523 is a micro-stepping stepper motor driver for bipolar stepper motors with an embedded CAN transceiver.

The motor driver is connected through I/O pins and a SPI interface with an external microcontroller. It has an on-chip voltage regulator, reset-output and watchdog reset, able to supply peripheral devices. It contains a current-translation table and takes the next micro-step depending on the clock signal on the "NXT" input pin and the status of the "DIR" (=direction) register or input pin.

The CAN transceiver is the interface between a (CAN) protocol controller and the physical bus. It provides differential transmit capability to the bus and differential receive capability to the CAN controller. To cope with the long bus delay the communication speed needs to be low. The integrated transceiver allows low transmit data rates down 10 kbit/s or lower.

The AMIS-30523 is ideally suited for general-purpose stepper motor applications in the automotive, industrial, medical, and marine environment. With the on-chip voltage regulator and embedded CAN transceiver it further reduces the BOM for mechatronic stepper applications.

## Key Features Motor Driver

- Dual H-Bridge for 2-Phase Stepper Motors
- Programmable Peak-Current up to 1.2 A Continuous (1.6 A for a Short Time)\*
- On-Chip Current Translator
- SPI Interface
- Seven Step Modes from Full Step up to 32 Micro-Steps
- PWM Current Control with Automatic Selection of Fast and Slow Decay and Fully Integrated Current-Sense
- Full Output Protection and Diagnosis
- Thermal Warning and Shutdown
- Integrated 5 V Regulator to Supply External Microcontroller

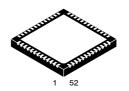
#### **CAN Transceiver**

- Compatible with the ISO 11898 Standard
- Wide Range of Bus Communication Speed (0 up to 1 Mbit/s)
- Allows Low Transmit Data Rate in Networks Exceeding 1 km
- Extremely Low Current Standby Mode with Wake-up via the Bus



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QFN52, 8x8 CASE 485M

#### MARKING DIAGRAM

1 o AMIS30523 0C523-001 XXXXYZZ

0C523-001 = Specific Device Code

XXXX = Date Code WL = Wafer Lot

Y = Assembly Location ZZ = Traceability Code

#### **ORDERING INFORMATION**

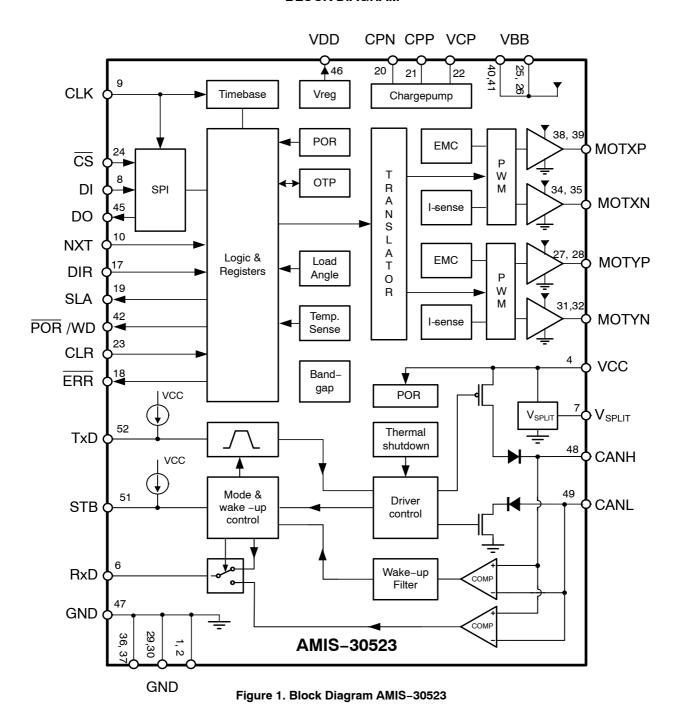
See detailed ordering and shipping information in the package dimensions section on page 34 of this data sheet.

- Low EME: Common–Mode Choke is No Longer Required
- Differential Receiver with Wide common–mode range (±35 V)
- Voltage Source via V<sub>SPLIT</sub> Pin for Stabilizing the Recessive Bus Level
- No Disturbance of the Bus Lines with an Un-Powered Node
- Logic Level Inputs Compatible with 3.3 V Devices
- These are Pb-Free Devices

\*Output Current Level May be Limited by Ambient Temperature and Heat Sinking

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

## **BLOCK DIAGRAM**



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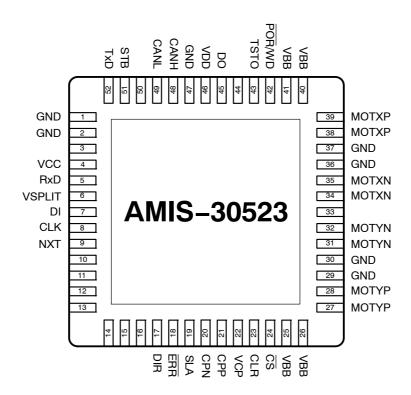


Figure 2. Pin Out AMIS-30523

**Table 1. PIN DESCRIPTION** 

Name	Pin	Description	Туре	Equivalent Schematic
GND	1, 2	Ground	Supply	
/	3	No function (to be left open in normal operation)		
VCC	4	CAN Supply voltage	Supply	
/	5	No function (to be left open in normal operation)		
RXD	6	CAN Receive data output; dominant transmitter → low output	Digital Output	
VSPLIT	7	CAN common-mode stabilization output	Supply	
DI	8	SPI Data In	Digital Input	Type 2
CLK	9	SPI Clock Input	Digital Input	Type 2
NXT	10	Next micro-step input	Digital Input	Type 2
/	11 16	No function (to be left open in normal operation)		
DIR	17	Direction input	Digital Input	Type 2
ERRB	18	Error output (open drain)	Digital Output	Type 4
SLA	19	Speed load angle output	Analog Output	Type 5
CPN	20	Negative connection of charge pump capacitor	High Voltage	
CPP	21	Positive connection of charge pump capacitor	High Voltage	
VCP	22	Charge pump filter-capacitor	High Voltage	
CLR	23	"Clear" = chip reset input	Digital Input	Type 1
CSB	24	SPI chip select input	Digital Input	Type 2
VBB	25, 26	High voltage supply Input	Supply	Type 3
MOTYP	27, 28	Negative end of phase Y coil output	Driver Output	
GND	29, 30	Ground, heat sink	Supply	

**Table 1. PIN DESCRIPTION** 

Name	Pin	Description	Туре	Equivalent Schematic
MOTYN	31, 32	Positive end of phase Y coil output	Driver Output	
/	33	No function (to be left open in normal operation)		
MOTXN	34, 35	Positive end of phase X coil output	Driver Output	
GND	36, 37	Ground, heat sink	Supply	
MOTXP	38, 39	Negative end of phase X coil output	Driver Output	
VBB	40, 41	High voltage supply input	Supply	Type 3
PORB/WD	42	Power-on-reset and watchdog reset output (open drain)	Digital Output	Type 2
TST0	43	Test pin input (to be tied to ground in normal operation)	Digital Input	
1	44	No function (to be left open in normal operation)		
DO	45	SPI data output (open drain)	Digital Output	Type 4
VDD	46	5V Logic Supply Output (needs external decoupling capacitor)	Supply	Type 6
GND	47	Ground	Supply	
CANH	48	High-level CAN bus line (high in dominant mode)	Analog Output	
CANL	49	Low-level CAN bus line (low in dominant mode)	Analog Output	
/	50	No function (to be left open in normal operation)		
STB	51	CAN stand-by mode control input	Digital Input	
TXD	52	CAN transmit data input; low input → dominant driver; internal pull-up current	Digital Input	

## **Table 2. ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Min	Max	Unit
$V_{BB}$	Analog DC supply voltage (Note 1)	-0.3	+40	٧
V <sub>CC</sub>	CAN Supply voltage	-0.3	+7	٧
V <sub>CANH</sub> , V <sub>CANL</sub> , V <sub>SPLIT</sub>	DC voltage CANH ,CANL and VSPLIT (Note 2)	-50	+50	V
V <sub>TRANS</sub>	Transient voltage CANH, CANL and VSPLIT (Note 3)	-300	+300	V
T <sub>ST</sub>	Storage temperature	-55	+150	°C
$T_J$	Junction Temperature under bias (Note 4)	-40	+170	°C
V <sub>ESD</sub>	Electrostatic discharges on component level, All pins (Note 5)	-2	+2	kV
V <sub>ESD</sub>	Electrostatic discharges on component level, All pins (Note 7)	-500	+500	V
V <sub>ESD</sub>	Electrostatic discharges on CANH, CANL and VSPLIT (Note 6)	-6	+6	kV
V <sub>ESD</sub>	Electrostatic discharges on CANH and CANL (Note 7)	-500	+500	٧
V <sub>ESD</sub>	Electrostatic discharges on component level, HiV pins (Note 6)	-6	+6	kV
Latch-up	Static latch-up at all pins		100	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- For limited time < 0.5 s.</li>
   For 0 < V<sub>CC</sub> < 5.25 V unlimited time</li>
- 3. Applied transient waveforms in accordance with ISO 7637 part 3, test pulses 1, 2, 3a, and 3b.
- 4. Circuit functionality not guaranteed.
- 5. Standardized Human body model (100 pF via 1.5 kΩ, according to JEDEC EIA–JESD22–A114–B).
- 6. Standardized human body model electrostatic discharge (ESD) pulses (100 pF via 1.5 kΩ) stressed pin to ground.
- 7. Standardized charged device model ESD pulses when tested according to ESD STM5.3.1-1999.

**Table 3. THERMAL RESISTANCE** 

		Thermal Resistance		
	Junction-to-Exposed Pad	Junction-to-Ar	mbient (Rth <sub>J-A</sub> )	
Package	(Rth <sub>J-EP</sub> )	1S0P Board	2S2P Board	Unit
QFN-52	0.95	60	30	K/W

## **EQUIVALENT SCHEMATICS**

Following figure gives the equivalent schematics of the user relevant inputs and outputs. The diagrams are simplified representations of the circuits used.

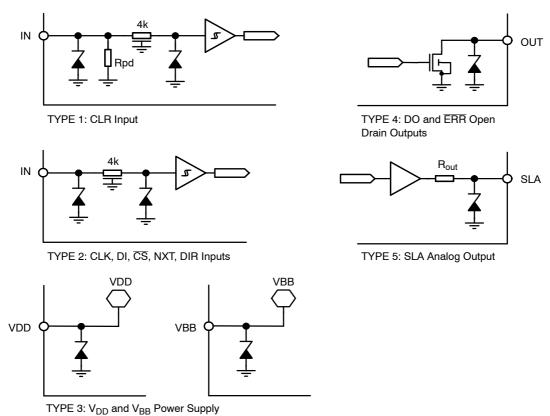


Figure 3. In- and Output Equivalent Diagrams

## PACKAGE THERMAL CHARACTERISTICS

The AMIS-30523 is available in a QFN-52 package. For cooling optimizations, the QFN has an exposed thermal pad which has to be soldered to the PCB ground plane. The ground plane needs thermal vias to conduct the heat to the bottom layer. Figure 4 gives an example for good power distribution solutions.

For precise thermal cooling calculations the major thermal resistances of the device are given. The thermal media to which the power of the devices has to be given are:

- Static environmental air (via the case)
- PCB board copper area (via the exposed pad)
   The thermal resistances are presented in Table 5: DC

   Parameters Motor Driver.

The major thermal resistances of the device are the Rth from the junction to the ambient ( $Rth_{J-A}$ ) and the overall Rth from the junction to exposed pad ( $Rth_{J-EP}$ ). In Table 3 one can find the values for the  $Rth_{J-A}$  and  $Rth_{J-EP}$ , simulated according to JESD-51:

The  $Rth_{J-A}$  for 2S2P is simulated conform JEDEC JESD-51 as follows:

- A 4-layer printed circuit board with inner power planes and outer (top and bottom) signal layers is used
- Board thickness is 1.46 mm (FR4 PCB material)
- The 2 signal layers: 70 μm thick copper with an area of 5500 mm<sup>2</sup> copper and 20% conductivity

- The 2 power internal planes: 36 µm thick copper with an area of 5500 mm<sup>2</sup> copper and 90% conductivity
   The Rth<sub>J-A</sub> for 1S0P is simulated conform JEDEC JESD-51 as follows:
- A 1-layer printed circuit board with a single power and signal layer
- Board thickness is 1.46 mm (FR4 PCB material)
- The layer has a thickness of 70 μm copper with an area of 5500 mm<sup>2</sup> copper and 20% conductivity

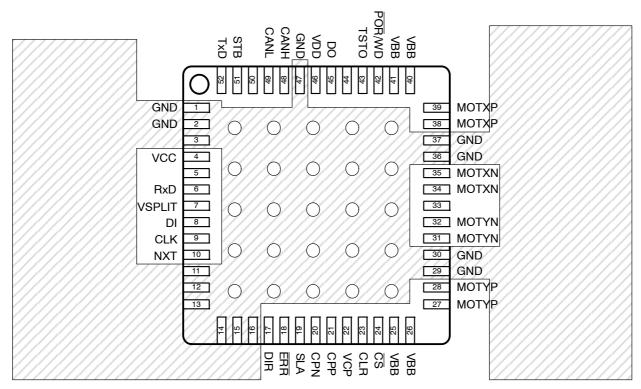


Figure 4. Example of QFN-52 PCB Ground Plane Layout in Top View (preferred layout at top and bottom)

#### **ELECTRICAL SPECIFICATION**

## **Recommend Operation Conditions**

Operating ranges define the limits for functional operation and parametric characteristics of the device. Note that the functionality of the chip outside these operating

ranges is not guaranteed. Operating outside the recommended operating ranges for extended periods of time may affect device reliability.

**Table 4. OPERATING RANGES** 

Symbol	Parameter	Min	Max	Unit
V <sub>BB</sub>	Motor Driver Analog DC supply	6	30	V
V <sub>CC</sub>	CAN transceiver DC supply	4.75	5.25	V
$T_J$	Junction temperature (Note 8)	-40	+172	°C

8. No more than 100 cumulative hours in life time above  $T_{tw}$ 

## **Table 5. DC PARAMETERS MOTOR DRIVER**

(The DC Parameters are Given for V<sub>BB</sub> and Temperature in Their Operating Ranges Unless Otherwise Specified) Convention: Currents Flowing in the Circuit are Defined as Positive.

Symbol	Pin(s)	Parameter	Remark/ Test Conditions	Min	Тур	Max	Unit
SUPPLY AN	D VOLTA	GE REGULATOR					
$V_{BB}$		Nominal operating supply range		6		30	V
I <sub>BB</sub>	VBB	Total internal current consumption	Unloaded outputs			8	mA
I <sub>BBS</sub>	1	Sleep current in V <sub>BB</sub> (Note 9)	Unloaded outputs			100	μΑ
$V_{DD}$		Regulated Output Voltage		4.50	5	5.50	V
I <sub>INT</sub>	1	Internal load current	Unloaded outputs			8	mA
I <sub>LOAD</sub>	\/DD	Max. Output Current (external and internal	6 V ≤ V <sub>BB</sub> < 8 V	15			mA
	VDD	loads)	$8 \text{ V} \leq \text{V}_{BB} \text{ v } 30 \text{ V}$	40			mA
I <sub>DDLIM</sub>	1	Current limitation	Pin shorted to ground			200	mA
I <sub>LOAD_PD</sub>	1	Output current in Power Down		1			mA
POWER ON	RESET (F	POR)					
$V_{DDH}$		Internal POR comparator threshold	VDD rising	3.9	4.15	4.4	V
$V_{DDL}$	VDD	Internal POR comparator threshold	VDD falling		3.80		V
V <sub>DDHYS</sub>		Hysteresis between V <sub>DDH</sub> and V <sub>DDL</sub>		0.1	0.35	0.6	V
MOTORDRI	VER						
I <sub>MDmax,Peak</sub>		Max current through motor coil in normal operation			1600		mA
I <sub>Mdmax,RMS</sub>	]	Max RMS current through coil in normal operation			800		mA
I <sub>Mdabs</sub>	1	Absolute error on coil current		-10		10	%
I <sub>Mdrel</sub>	1	Error on current ratio I <sub>coilx</sub> / I <sub>coily</sub>		-7		7	%
I <sub>SET_TC1</sub>		Temperature coefficient of coil current set-level, CUR[4:0] = 0 27 (Note 10)	-40 °C ≤ T <sub>J</sub> ≤ 160°C		-240		ppm/K
I <sub>SET_TC2</sub>		Temperature coefficient of coil current set-level, CUR[4:0] = 28 31 (Note 10)	-40 °C ≤ T <sub>J</sub> ≤ 160°C		-490		ppm/K
R <sub>HS</sub>	MOTXP	On-resistance high-side driver,	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 27°C		0.45	0.56	Ω
	MOTXN MOTYP	CUR[4:0] = 0 31	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 160°C		0.94	1.25	Ω
R <sub>LS3</sub>	MOTYN	On-resistance low-side driver,	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 27°C		0.45	0.56	Ω
		CUR[4:0] = 23 31	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 160°C		0.94	1.25	Ω
R <sub>LS2</sub>	1	On-resistance low-side driver,	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 27°C		0.90	1.2	Ω
		CUR[4:0] = 16 22	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 160°C		1.9	2.5	Ω
R <sub>LS1</sub>	1	On-resistance low-side driver,	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 27°C		1.8	2.3	Ω
		CUR[4:0] = 9 15	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 160°C		3.8	5.0	Ω
R <sub>LS0</sub>	1	On-resistance low-side driver,	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 27°C		3.6	4.5	Ω
		CUR[4:0] = 0 8	V <sub>BB</sub> = 12 V, T <sub>J</sub> = 160°C		7.5	10	Ω
I <sub>Mpd</sub>	1	Pull down current motor pins	HiZ mode		1		mA

<sup>9.</sup> Characterization Data Only, not tested in production 10. The coil current at a given junction temperature is calculated as: I<sub>coil</sub> @ T<sub>J</sub> = I<sub>coil</sub> [1 + (T<sub>J</sub> - 125) x I<sub>SET\_TCi</sub> x 10<sup>-6</sup>]. See also paragraph Programmable Peak Current.

<sup>11.</sup> Not valid for pins with internal Pull Down resistor.

<sup>12.</sup> No more than 100 cumulated hours in life time above  $T_{tw}$ .

<sup>13.</sup> Thermal shutdown is derived from Thermal Warning.

## **Table 5. DC PARAMETERS MOTOR DRIVER**

(The DC Parameters are Given for V<sub>BB</sub> and Temperature in Their Operating Ranges Unless Otherwise Specified) Convention: Currents Flowing in the Circuit are Defined as Positive.

Symbol	Pin(s)	Parameter	Remark/ Test Conditions	Min	Тур	Max	Unit
DIGITAL INF	PUTS		•	<b>-</b>			
I <sub>leak</sub>	DI, CLK	Input Leakage (Note 11)	T <sub>J</sub> = 160°C			1	μА
V <sub>IL</sub>	NXT, DIR	Logic Low Threshold		0		0.65	V
V <sub>IH</sub>	CLR, CSB	Logic High Threshold		2.20		$V_{DD}$	V
R <sub>pd_CLR</sub>	CLR	Internal Pull Down Resistor		120		300	kΩ
R <sub>pd_TST</sub>	TST0	Internal Pull Down Resistor		3		9	kΩ
DIGITAL OU	TPUTS			•			
V <sub>OL</sub>	DO, ERRB, PORB/ WD	Logic Low level open drain	I <sub>OL</sub> = 5 mA			0.3	V
THERMAL V	WARNING	& SHUTDOWN					
$T_{tw}$		Thermal Warning		138	145	152	°C
$T_{tsd}$		Thermal shutdown (Notes 12 and 13)			$T_{tw} + 20$		°C
CHARGE P	UMP						
$V_{opCP}$	VOD	Output voltage	6 V< V <sub>BB</sub> < 15 V		2 * V <sub>BB</sub> - 2		V
	VCP		15 V < V <sub>BB</sub> < 30 V	V <sub>BB</sub> + 9	V <sub>BB</sub> + 11.5	V <sub>BB</sub> + 16	V
PACKAGE 1	THERMAL	RESISTANCE VALUE	•	4			
Rth <sub>J-A</sub>	QFN	Thermal Resistance Junction-to-Ambient	Simulated Conform JEDEC JESD-51, (2S2P)		30		K/W
Rth <sub>J-EP</sub>	package	Thermal Resistance Junction-to-Exposed Pad			0.95		K/W
SPEED AND	LOAD A	NGLE OUTPUT					
V <sub>out</sub>		Output Voltage Range		0.2		V <sub>DD</sub> - 0.2	V
V <sub>off</sub>		Output Offset SLA pin		-50		50	mV
G <sub>sla</sub>	SLA	Gain of SLA Pin = V <sub>BEMF</sub> / V <sub>COIL</sub>	SLAG = 0		0.5		
			SLAG = 1		0.25		
R <sub>out</sub>		Output Resistance SLA pin	(Note 9)		0.23	1	kΩ
C <sub>load</sub>		Load Capacitance SLA pin	(Note 9)			50	pF

<sup>9.</sup> Characterization Data Only, not tested in production
10. The coil current at a given junction temperature is calculated as: I<sub>coil</sub> @ T<sub>J</sub> = I<sub>coil</sub> [1 + (T<sub>J</sub> - 125) x I<sub>SET\_TCi</sub> x 10<sup>-6</sup>]. See also paragraph Programmable Peak Current.
11. Not valid for pins with internal Pull Down resistor.

<sup>12.</sup> No more than 100 cumulated hours in life time above Ttw.

<sup>13.</sup> Thermal shutdown is derived from Thermal Warning.

 $\textbf{Table 6. AC PARAMETERS MOTOR DRIVER} \ (\textbf{The AC Parameters are Given for V}_{BB} \ \textbf{and Temperature in Their Operating Ranges})$ 

Pin(s)	Parameter	Remark/ Test Conditions	Min	Тур	Max	Unit
SCILLAT	OR					
	Frequency of internal oscillator		3.6	4	4.4	MHz
/ER						
	PWM frequency	Frequency depends only	20.8	22.8	24.8	kHz
MOTxx	Double PWM frequency	on internal oscillator	41.6	45.6	49.6	kHz
	PWM jitter Depth (Note 14)			10		% f <sub>PWM</sub>
	Turn-on voltage slope, 10% to 90%	EMC[1:0] = 00		150		V/μs
MOTrac		EMC[1:0] = 01		100		V/μs
MOTXX		EMC[1:0] = 10		50		V/μs
		EMC[1:0] = 11		25		V/μs
	Turn-off voltage slope, 90% to 10%	EMC[1:0] = 00		150		V/μs
MOT		EMC[1:0] = 01		100		V/μs
MOTXX		EMC[1:0] = 10		50		V/μs
		EMC[1:0] = 11		25		V/μs
PUTS						
DO ERRB	Output fall-time from V <sub>inH</sub> to V <sub>inL</sub> (Note 14)	Capacitive load 400 pF and pull-up resistor of 1.5 k $\Omega$			50	ns
MP						
CPN CPP	Charge pump frequency			250		kHz
MOTxx	Start-up time of charge pump (Note 14)	Spec external components See Table 10			5	ms
ON		•				1
CLR	Hard reset duration time		100			μs
		•				1
DODR/	Power-up time	V <sub>BB</sub> = 12 V, I <sub>LOAD</sub> = 50 mA, C <sub>LOAD</sub> = 220 nF			110	μs
WD	Reset duration	See Figure 22			100	ms
	Reset filter time	See Figure 22	1			μs
		•				1
PORB/	Watchdog time out interval	See Figure 23	32		512	ms
WD	Prohibited watchdog acknowledge delay	See Figure 23		2		ms
ON						•
	NXT Minimum, High Pulse Width	See Figure 5	2			μs
	NXT Minimum, Low Pulse Width	See Figure 5	2			μs
NXT	NXT Hold Time, Following Change of DIR	See Figure 5		2		μs
	NXT Hold Time, Before Change of DIR	See Figure 5		2		μs
	MOTXX  MOTXX  MOTXX  PUTS  DO ERRB  MP  CPN CPP  MOTXX  ON CLR  PORB/ WD	MOTXX PWM frequency Double PWM frequency PWM jitter Depth (Note 14)  Turn-on voltage slope, 10% to 90%  MOTXX  Turn-off voltage slope, 90% to 10%  MOTXX  DO ERRB  Output fall-time from V <sub>inH</sub> to V <sub>inL</sub> (Note 14)  MP  CPN CPP CPP Charge pump frequency CPP MOTXX  Start-up time of charge pump (Note 14)  ON  CLR Hard reset duration time  PORB/WD Reset duration Reset filter time  PORB/WD  PORB/WD  NXT Minimum, High Pulse Width NXT Mold Time, Following Change of DIR	Frequency of internal oscillator	Frequency of internal oscillator   3.6     Frequency   Frequency	Frequency of internal oscillator	Frequency of internal oscillator

<sup>14.</sup> Characterization Data Only, not tested in production.

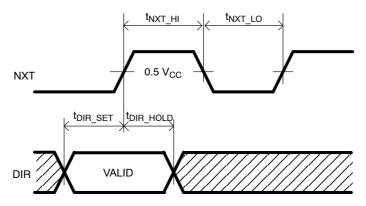


Figure 5. NXT-Input Timing Diagram

**Table 7. SPI TIMING PARAMETERS** 

Symbol	Parameter	Min	Тур	Max	Unit
t <sub>CLK</sub>	SPI clock period	1			μs
tclk_High	SPI clock high time	100			ns
tclk_low	SPI clock low time	100			ns
t <sub>SET_DI</sub>	DI set up time, valid data before rising edge of CLK	50			ns
t <sub>HOLD_DI</sub>	DI hold time, hold data after rising edge of CLK	50			ns
t <sub>CSB_HIGH</sub>	CSB high time	2.5			μs
t <sub>SET_CSB</sub>	CSB set up time, CSB low before rising edge of CLK	100			ns
t <sub>SET_CLK</sub>	CLK set up time, CLK low before rising edge of CSB	100			ns

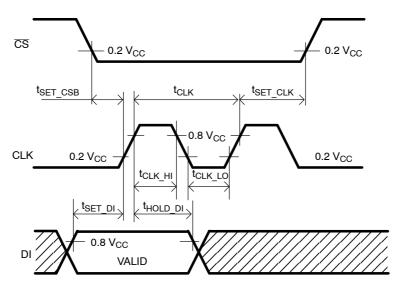


Figure 6. SPI Timing

## Table 8. DC PARAMETERS CAN TRANSCEIVER

(The DC parameters are given for  $V_{CC}$  and temperature in its operating range;  $T_J = -40$  to  $+150^{\circ}$ C;  $R_{LT} = 60 \Omega$  unless otherwise specified) Convention: currents flowing in the circuit are defined as positive.

Symbol	Pin(s)	Parameter	Remark / Test Conditions	Min	Тур	Max	Unit
UPPLY							
I <sub>CC</sub>	VCC	Supply current	Dominant; $V_{TxD} = 0 V$ Recessive; $V_{TxD} = V_{CC}$		45	65	mA
I <sub>CCS</sub>		Supply current in standby mode	T <sub>J,max</sub> = 100°C		4	8	mA
RANSMITT	TER DATA	INPUT					
$V_{iH}$		High-level input voltage	CAN bus output recessive	2.0	-	V <sub>CC</sub> + 0.3	V
V <sub>iL</sub>	TYD	Low-level input voltage	CAN bus output dominant	-0.3	=	+0.8	V
I <sub>iH</sub>	IXD	High-level input current	$V_{TxD} = V_{CC}$	-5	0	+5	μΑ
l <sub>iL</sub>		Low-level input current	$V_{TxD} = 0 V$	-75	-200	-350	μΑ
C <sub>i</sub>		Input capacitance	(Note 15)	-	5	10	pF
RANSMIT	TER MODE	SELECT	•	-	-	-	
$V_{iH}$		High-level input voltage	Standby mode	2.0	_	V <sub>CC</sub> + 0.3	V
$V_{iL}$		Low-level input voltage	Normal mode	-0.3	-	+0.8	V
I <sub>iH</sub>	TXD	High-level input current	V <sub>STB</sub> = V <sub>CC</sub>	-5	0	+5	μΑ
I <sub>iL</sub>		Low-level input current	V <sub>STB</sub> = 0 V	-1	-4	-10	μΑ
C <sub>i</sub>		Input capacitance	(Note 15)	-	5	10	pF
ECEIVER	DATA OUT	ГРИТ					
V <sub>OH</sub>		High-level output voltage	I <sub>RXD</sub> = -10 mA	0.6 x V <sub>CC</sub>		0.75 x V <sub>CC</sub>	V
V <sub>OL</sub>		Low-level output voltage	I <sub>RXD</sub> = 5 mA		0.25	0.45	V
l <sub>oh</sub>	RXD	High-level output current	$V_0 = 0.7 \times V_{CC}$	-5	-10	-15	mA
l <sub>ol</sub>		Low-level output current	$V_0 = 0.3 \times V_{CC}$	5	10	15	mA
Ci	TXD  ER MODE  TXD	Input capacitance	(Note 15)	-	5	10	pF

<sup>15.</sup> Characterization Data Only, not tested in production.

## Table 8. DC PARAMETERS CAN TRANSCEIVER

(The DC parameters are given for  $V_{CC}$  and temperature in its operating range;  $T_J = -40$  to  $+150^{\circ}C$ ;  $R_{LT} = 60 \Omega$  unless otherwise specified) Convention: currents flowing in the circuit are defined as positive.

Symbol	Pin(s)	Parameter	Remark / Test Conditions	Min	Тур	Max	Unit
BUS LINES							•
V <sub>o(reces)</sub> (norm)		Recessive bus voltage	V <sub>TxD</sub> = V <sub>CC</sub> ; no load normal mode	2.0	2.5	3.0	V
V <sub>o(reces)</sub> (stby)		Recessive bus voltage	V <sub>TxD</sub> = V <sub>CC</sub> ; no load standby mode	-100	0	100	mV
I <sub>o(reces)</sub> (CANH)		Recessive output current at pin CANH	-35 V < V <sub>CANH</sub> < +35 V; 0 V < V <sub>CC</sub> < 5.25 V	-2.5	-	+2.5	mA
I <sub>o(reces)</sub> (CANL)		Recessive output current at pin CANL	-35 V <v<sub>CANL &lt; +35 V; 0 V <v<sub>CC &lt; 5.25 V</v<sub></v<sub>	-2.5	-	+2.5	mA
V <sub>o(dom)</sub> (CANH)		Dominant output voltage at pin CANH	V <sub>TxD</sub> = 0 V	3.0	3.6	4.25	V
V <sub>o(dom)</sub> (CANL)		Dominant output voltage at pin CANL	V <sub>TxD</sub> = 0 V	0. 5	1.4	1.75	V
V <sub>o(dif)</sub> (bus_dom)		Differential bus output voltage (VCANH - VCANL)	$V_{TxD}$ = 0 V; dominant; 42.5 $\Omega$ < R <sub>LT</sub> < 60 $\Omega$	1.5	2.25	3.0	V
V <sub>o(dif)</sub> (bus_rec)	CANH	Differential bus output voltage (V <sub>CANH</sub> - V <sub>CANL</sub> )	V <sub>TxD</sub> = V <sub>CC</sub> ; recessive; no load	-120	0	+50	mV
I <sub>o(sc)</sub> (CANH)	CANL	Short circuit output current at pin CANH	V <sub>CANH</sub> = 0 V; V <sub>TxD</sub> = 0 V	-45	-70	-120	mA
I <sub>o(sc)</sub> (CANL)		Short circuit output current at pin CANL	V <sub>CANL</sub> = 36 V; V <sub>TxD</sub> = 0 V	45	70	120	mA
V <sub>i(dif) (th)</sub>		Differential receiver threshold voltage (see Figure 8)	-5 V < V <sub>CANL</sub> < +12 V; -5 V < V <sub>CANH</sub> < +12 V;	0.5	0.7	0.9	V
V <sub>ihcm(dif) (th)</sub>		Differential receiver threshold voltage for high common–mode (see Figure 8))	-35 V < V <sub>CANL</sub> < +35 V; -35 V < V <sub>CANH</sub> < +35 V;	0.40	0.7	1.00	V
V <sub>i(dif) (hys)</sub>		Differential receiver input voltage hysteresis (see Figure 8)	-35 V < V <sub>CANL</sub> < +35 V; -35 V < V <sub>CANH</sub> < +35 V;	50	70	100	mV
R <sub>i(cm)</sub> (CANH)		Common-mode input resistance at pin CANH		15	26	37	kΩ
R <sub>i(cm)</sub> (CANL)		Common-mode input resistance at pin CANL		15	26	37	kΩ
R <sub>i(cm) (m)</sub>		Matching between pin CANH and pin CANL common mode input resistance	V <sub>CANH</sub> = V <sub>CANL</sub>	-3	0	+3	%
R <sub>i(dif)</sub>	1	Differential input resistance		25	50	75	kΩ
C <sub>i(CANH)</sub>		Input capacitance at pin CANH	$V_{TxD} = V_{CC}$ ; (Note 15)		7.5	20	pF
C <sub>i(CANL)</sub>	CANH CANL	Input capacitance at pin CANL	V <sub>TxD</sub> = V <sub>CC</sub> ; (Note 15)		7.5	20	pF
C <sub>i(dif)</sub>		Differential input capacitance	V <sub>TxD</sub> = V <sub>CC</sub> ; (Note 15)		3.75	10	pF
COMMON-N	IODE STA	BILIZATION					
V <sub>SPLIT</sub>	VODUT	Reference output voltage at pin V <sub>SPLIT</sub>	Normal mode; -500 μA < I <sub>SPLIT</sub> < 500 μA	0.3 x V <sub>CC</sub>	_	0.7 x V <sub>CC</sub>	
I <sub>SPLIT(i)</sub>	VSPLIT	V <sub>SPLIT</sub> leakage current	Stand-by mode	-5		+5	μΑ
I <sub>SPLIT(lim)</sub>	1	V <sub>SPLIT</sub> limitation current	Normal mode	-3		+3	mA
POWER ON	RESET (P				1	<u>I</u>	<u> </u>
PORL		POR level	CANH, CANL, V <sub>ref</sub> in tri–state below POR level	2.2	3.5	4.7	V

<sup>15.</sup> Characterization Data Only, not tested in production.

## **Table 9. AC PARAMETER CAN TRANSCEIVER**

The AC parameters are given for  $V_{CC}$  and temperature in its operating range;  $T_J = -40$  to  $+150^{\circ}C$ ;  $R_{LT} = 60~\Omega$  unless otherwise specified

Symbol	Din(a)	Devementor	Remark / Test Conditions	Min	Time	May	l lmit
Symbol	Pin(s)	Parameter	rest conditions	Min	Тур	Max	Unit
TIMING CHAR	RACTERI	STICS					
t <sub>d(TxD-BUSon)</sub>		Delay TXD to bus active	C <sub>I</sub> = 100 pF between CANH to CANL	40	85	105	ns
t <sub>d(TxD-BUSoff)</sub>		Delay TXD to bus inactive	C <sub>I</sub> = 100 pF between CANH to CANL	30	60	105	ns
t <sub>d(BUSon-RXD)</sub>		Delay bus active to RXD	C <sub>rxd</sub> = 15 pF	25	55	105	ns
t <sub>d(BUSoff-RXD)</sub>		Delay bus inactive to RXD	C <sub>rxd</sub> = 15 pF	40	100	105	ns
t <sub>pd(rec-dom)</sub>		Propagation delay TXD to RXD from recessive to dominant	C <sub>I</sub> = 100 pF between CANH to CANL	90		230	ns
t <sub>d(dom-rec)</sub>		Propagation delay TXD to RXD from dominant to recessive	C <sub>I</sub> = 100 pF between CANH to CANL	90		245	ns
t <sub>d(stb-nm)</sub>		Delay standby mode to normal mode		5	7.5	10	μs
t <sub>dbus</sub>		Dominant time for wake-up via bus		0.75	2.5	5	μs

<sup>16.</sup> Characterization Data Only, not tested in production

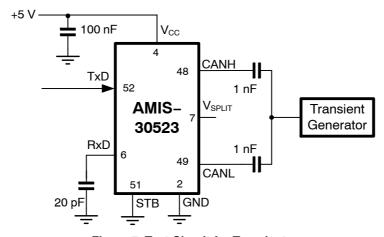


Figure 7. Test Circuit for Transients

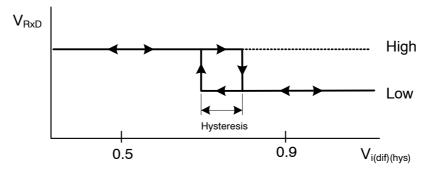


Figure 8. Hysteresis of the Receiver

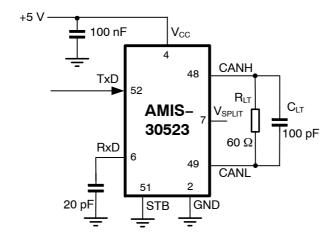


Figure 9. Test Circuit for Timing Characteristics

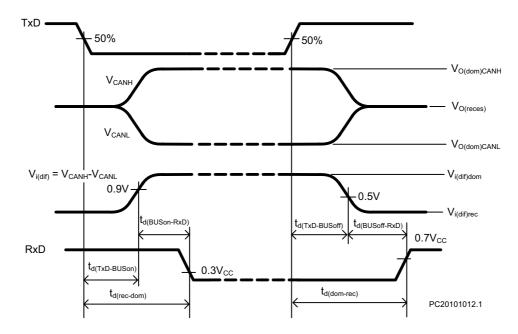


Figure 10. Timing Diagram for AC Characteristics

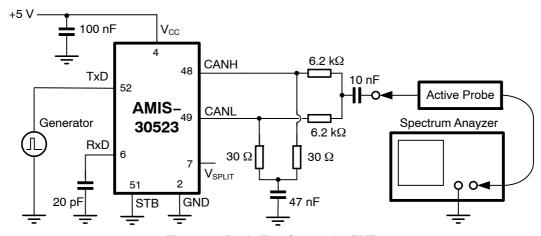


Figure 11. Basic Test Set-up for EME

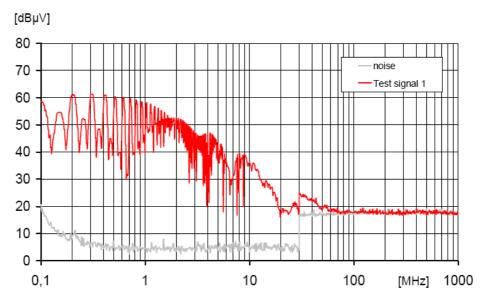


Figure 12. EME Measurements

## TYPICAL APPLICATION SCHEMATIC

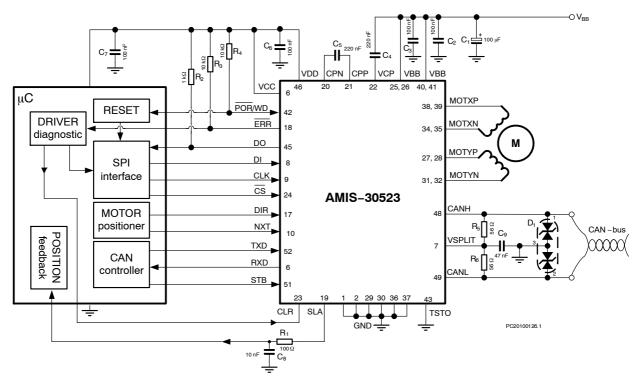


Figure 13. Typical Application Schematic AMIS-30523

Table 10. EXTERNAL COMPONENTS LIST AND DESCRIPTION

Component	Function	Typ Value	Tolerance	Unit
C <sub>1</sub>	V <sub>BB</sub> buffer capacitor (Note 17)	100	-20 +80%	μF
C <sub>2</sub> , C <sub>3</sub>	V <sub>BB</sub> decoupling block capacitor	100	-20 +80%	nF
C <sub>4</sub>	Charge-pump pumping capacitor	220	±20%	nF
C <sub>5</sub>	Charge-pump buffer capacitor	220	±20%	nF
C <sub>6</sub> , C <sub>7</sub>	V <sub>DD</sub> buffer capacitor	100	±20 %	nF
C <sub>8</sub>	Low pass filter SLA	10	±20%	nF
C <sub>9</sub>	VSPLIT decoupling capacitor	47	±20%	nF
R <sub>1</sub>	Low pass filter SLA	100	± 1%	Ω
R <sub>2</sub>	Pull up resistor open drain DO output	1	± 1%	kΩ
R <sub>3</sub> , R <sub>4</sub>	Pull up resistor open drain output	10	± 1%	kΩ
R <sub>5</sub> , R <sub>6</sub>	CAN termination resistors	56	± 1%	Ω
D <sub>1</sub>	CAN protection diode	NUP2105		

17. Low ESR < 1  $\Omega$ .

#### **FUNCTIONAL DESCRIPTION MOTOR DRIVER**

#### Introduction

The AMIS-30523 is a micro-stepping stepper motor driver for bipolar stepper motors embedded with an integrated CAN transceiver.

The motor driver is connected through I/O pins and a SPI interface with an external microcontroller. It has an on-chip voltage regulator, reset-output and watchdog reset, able to supply peripheral devices. It contains a current-translation table and takes the next micro-step depending on the clock signal on the "NXT" input pin and the status of the "DIR" (=direction) register or input pin. A proprietary PWM algorithm is used for reliable current control. The motor driver provides a so-called "speed and load angle" output. This allows the creation of stall detection algorithms and control loops based on load-angle to adjust torque and speed.

## **H-Bridge Drivers**

A full H-bridge is integrated for each of the two stator windings. Each H-bridge consists of two low-side and two high-side N-type MOSFET switches. Writing logic '0' in bit <MOTEN> disables all drivers (high-impedance). Writing logic '1' in this bit enables both bridges and current can flow in the motor stator windings.

In order to avoid large currents through the H-bridge switches, it is guaranteed that the top- and bottom-switches of the same half-bridge are never conductive simultaneously (interlock delay).

A two-stage protection against shorts on motor lines is implemented. In a first stage, the current in the driver is limited. Secondly, when excessive voltage is sensed across the transistor, the transistor is switched off.

In order to reduce the radiated/conducted emission, voltage slope control is implemented in the output switches. The output slope is defined by the gate—drain capacitance of output transistor and the (limited) current that drives the gate. There are two trimming bits for slope control (see Table 15 SPI Control Parameter Overview EMC[1:0]).

The power transistors are equipped with so-called "active diodes": when a current is forced trough the transistor switch in the reverse direction, i.e. from source to drain, then the transistor is switched on. This ensures that most of the current flows through the channel of the transistor instead of through the inherent parasitic drain-bulk diode of the transistor.

Depending on the desired current range and the micro-step position at hand, the  $R_{DS(on)}$  of the low-side transistors will be adapted such that excellent current-sense accuracy is maintained. The  $R_{DS(on)}$  of the high-side transistors remain unchanged; see Table 5 DC Parameters Motor driver, for more details.

#### **PWM Current Control**

A PWM comparator compares continuously the actual winding current with the requested current and feeds back the information to a digital regulation loop. This loop then generates a PWM signal, which turns on/off the H-bridge switches. The switching points of the PWM duty-cycle are synchronized to the on-chip PWM clock. The frequency of the PWM controller can be doubled and an artificial jitter can be added (see Table 15 SPI Control Parameter Overview PWMJ). The PWM frequency will not vary with changes in the supply voltage. Also variations in motor-speed or load-conditions of the motor have no effect. There are no external components required to adjust the PWM frequency.

#### Automatic Forward and Slow-Fast Decay

The PWM generation is in steady-state using a combination of forward and slow-decay. The absence of fast-decay in this mode, guarantees the lowest possible current-ripple "by design". For transients to lower current levels, fast-decay is automatically activated to allow high-speed response. The selection of fast or slow decay is completely transparent for the user and no additional parameters are required for operation.

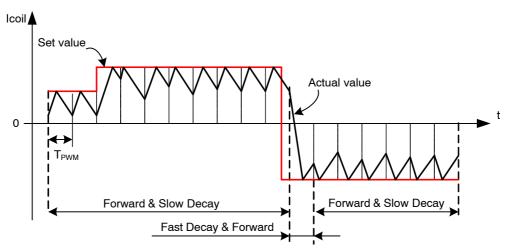


Figure 14. Forward and Slow/Fast Decay PWM

#### **Automatic Duty Cycle Adaptation**

In case the supply voltage is lower than 2 \* Bemf, then the duty cycle of the PWM is adapted automatically to >50% to maintain the requested average current in the coils. This

process is completely automatic and requires no additional parameters for operation. The over-all current-ripple is divided by two if PWM frequency is doubled (see Table 15 SPI Control Parameter Overview PWMF)

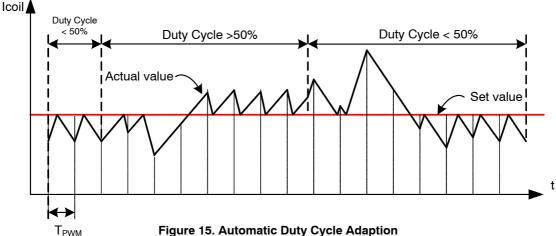


Figure 15. Automatic Duty Cycle Adaption

## **Step Translator and Step Mode**

The step translator provides the control of the motor by means of SPI register Stepmode: SM[2:0], SPI register DIRCNTRL and input pins DIR and NXT. It is translating consecutive steps in corresponding currents in both motor coils for a given step mode.

One out of seven possible stepping modes can be selected through SPI-bits SM[2:0] (see Table 15 SPI Control Parameter Overview ) After power-on or hard reset, the coil-current translator is set to the default 1/32 micro-stepping at position '0'. Upon changing the step mode, the translator jumps to position 0\* of the

corresponding stepping mode. When remaining in the same step mode, subsequent translator positions are all in the same column and increased or decreased with 1. Table 12 lists the output current vs. the translator position.

As shown in Figure 16 the output current-pairs can be projected approximately on a circle in the (I<sub>x</sub>,I<sub>v</sub>) plane. There are, however, two exceptions: uncompensated half step and full step. In these step modes the currents are not regulated to a fraction of I<sub>max</sub> but are in all intermediate steps regulated at 100%. In the (I<sub>x</sub>,I<sub>v</sub>) plane the current-pairs are projected on a square. Table 11 lists the output current vs. the translator position for these cases.

Table 11. SQUARE TRANSLATOR TABLE FOR FULL STEP AND UNCOMPENSATED HALF STEP

	Stepmode ( SM	N[2:0] )	% of Ima		
	101	110			
MSP[6:0]	Uncompensated Half-Step	Full Step	Coil x	Coil y	
000 0000	0	-	0	100	
001 0000	1	1	100	100	
010 0000	2	-	100	0	
011 0000	3	2	100	-100	
100 0000	4	-	0	-100	
101 0000	5	3	-100	-100	
110 0000	6	-	-100	0	
111 0000	7	0	-100	100	

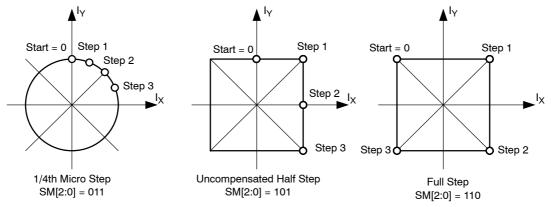


Figure 16. Translator Table: Circular and Square

**Table 12. CIRCULAR TRANSLATOR TABLE** 

		Stepmode (SM[2:0])					% of I <sub>max</sub>		
	000	001	010	011	100				
MSP[6:0]	1/32	1/16	1/8	1/4	1/2	Coil x	Coil y		
000 0000	<b>'</b> 0'	0*	0*	0*	0*	0	100		
000 0001	1	_	-	_	_	3.5	98.8		
000 0010	2	1	-	_	_	8.1	97.7		
000 0011	3	-	_	_	-	12.7	96.5		
000 0100	4	2	1	_	-	17.4	95.3		
000 0101	5	-	-	_	_	22.1	94.1		
000 0110	6	3	_	_	_	26.7	93		
000 0111	7		_	-	-	31.4	91.8		
000 1000	8	4	2	1	_	34.9	89.5		
000 1001 000 1010	9 10	_ 5	<u> </u>	_	_	38.3 43	87.2 84.9		
000 1010	11			_ _	<u> </u>	46.5	82.6		
000 1011	12	6	3	_	_	50	79		
000 1101	13	_	_	_	_	54.6	75.5		
000 1110	14	7	_	_	_	58.1	72.1		
000 1111	15	_	_	_	_	61.6	68.6		
001 0000	16	8	4	2	1	65.1	65.1		
001 0001	17	_	-	_	_	68.6	61.6		
001 0010	18	9	-	_	_	72.1	58.1		
001 0011	19	-	-	_	-	75.5	54.6		
001 0100	20	10	5	-	_	79	50		
001 0101	21	-	-	_	_	82.6	46.5		
001 0110	22	11	-	-	-	84.9	43		
001 0111	23	-	_	_	_	87.2	38.3		
001 1000	24	12	6	3	-	89.5	34.9		
001 1001	25	-	-	_	_	91.8	31.4		
001 1010	26 27	13	_	_	_	93 94.1	26.7 22.1		
001 1011 001 1100	28	_ 14	7	_		95.3			
001 1100	29	14 	-			96.5	17.4 12.7		
001 1110	30	15	_	_	_	97.7	8.1		
001 1111	31	-	_	_	_	98.8	3.5		
010 0000	32	16	8	4	2	100	0		
010 0001	33	-	_	_	_	98.8	-3.5		
010 0010	34	17	-	_	_	97.7	-8.1		
010 0011	35	_	_	_	_	96.5	-12.7		
010 0100	36	18	9	_	_	95.3	-17.4		
010 0101	37	_	-	_	-	94.1	-22.1		
010 0110	38	19	-	_	-	93	-26.7		
010 0111	39		-	_	-	91.8	-31.4		
010 1000	40	20	10	5	_	89.5	-34.9		
010 1001 010 1010	41 42	- 21		_	_	87.2 84.9	-38.3 -43		
010 1010	43	<u> </u>		-	_	82.6	-43 -46.5		
010 1011	44	22	11	_ _	<u> </u>	79	-40.5 -50		
010 1101	45		-	_	_	75.5	-54.6		
010 1110	46	23	_	_		72.1	-54.0 -58.1		
010 1111	47	-	_	_	_	68.6	-61.6		
011 0000	48	24	12	6	3	65.1	-65.1		
011 0001	49	-	-	-	_	61.6	-68.6		
011 0010	50	25	_	_	-	58.1	-72.1		
011 0011	51	-	-	-	-	54.6	-75.5		
011 0100	52	26	13	-	-	50	-79		
011 0101	53	-	-	_	_	46.5	-82.6		
011 0110	54	27	-	-	-	43	-84.9		
011 0111	55	-	-	<u>-</u>	-	38.3	-87.2		
011 1000	56	28	14	7	_	34.9	-89.5		
011 1001	57	-	-	_	-	31.4	-91.8		
011 1010	58	29	_	_	_	26.7	-93		
011 1011 011 1100	59 60	30	_ 15	-	-	22.1 17.4	-94.1 -95.3		
011 1100	61	-	15  -			17.4	-95.3 -96.5		
011 1110	62	31				8.1	-90.5 -97.7		
U11 1110	63	U I				3.5	-97.7 -98.8		

Table 12. CIRCULAR TRANSLATOR TABLE

		Stepmode ( SM[2:0] )				% of Imax		
	000	001	010	011	100	1		
MSP[6:0]	1/32	1/16	1/8	1/4	1/2	Coil x	Coil y	
100 0000	64	32	16	8	4	0	-100	
100 0001	65	-	-	_	_	-3.5	-98.8	
100 0010	66	33	_	_	_	-8.1	-97.7	
100 0011	67	_	_	_	_	-12.7	-96.5	
100 0100	68	34	17	_	_	-17.4	-95.3	
100 0101	69	_	_	_	_	-22.1	-94.1	
100 0110	70	35	_	_	_	-26.7	-93	
100 0111	71	_	_	_	-	-31.4	-91.8	
100 1000	72	36	18	9	-	-34.9	-89.5	
100 1001	73 74	- 37	_	_	_	-38.3	-87.2	
100 1010 100 1011	74 75	- -	_ _	_ _	<u> </u>	-43 -46.5	-84.9 -82.6	
100 1011	76	38	 19			-40.5 -50	-62.0 -79	
100 1100	77					-54.6	-79 -75.5	
100 1110	78	39	-	_	_	-54.0 -58.1	-73.3 -72.1	
100 1111	79	-	_	_	_	-61.6	-68.6	
101 0000	80	40	20	10	5	-65.1	-65.1	
101 0001	81	-	-	-	-	-68.6	-61.6	
101 0010	82	41	-	-	-	-72.1	-58.1	
101 0011	83	_	_	_	-	-75.5	-54.6	
101 0100	84	42	21	_	-	-79	-50	
101 0101	85	-	-	-	-	-82.6	-46.5	
101 0110	86	43	_	_	_	-84.9	-43	
101 0111	87	_	_	_	-	-87.2	-38.3	
101 1000	88	44	22	11	-	-89.5	-34.9	
101 1001	89		_	-	-	-91.8	-31.4	
101 1010	90	45	_	_	-	-93	-26.7	
101 1011	91	-	-	_	-	-94.1	-22.1	
101 1100	92	46 _	23	_ _		-95.3	-17.4 -12.7	
101 1101 101 1110	93 94	47				-96.5 -97.7	-12.7 -8.1	
101 1111	95	-				-97.7 -98.8	-3.5	
110 0000	96	48	24	12	6	-100	0	
110 0001	97	-	_	_	_	-98.8	3.5	
110 0010	98	49	_	_	_	-97.7	8.1	
110 0011	99	_	_	_	_	-96.5	12.7	
110 0100	100	50	25	_	-	-95.3	17.4	
110 0101	101	_	_	_	_	-94.1	22.1	
110 0110	102	51	_	-	-	-93	26.7	
110 0111	103	_	_	_	_	-91.8	31.4	
110 1000	104	52	26	13	-	-89.5	34.9	
110 1001	105	-	_	_	-	-87.2	38.3	
110 1010	106	53	_	_	_	-84.9	43	
110 1011 110 1100	107 108	- 54	- 27	_	_	-82.6 -79	46.5 50	
110 1100	108	54 _			_	-79 -75.5	54.6	
110 1110	110	 55	_ _	<u> </u>		-73.5 -72.1	58.1	
110 1111	111			_		-68.6	61.6	
111 0000	112	56	28	14	7	-65.1	65.1	
111 0001	113	-	-	-	_	-61.6	68.6	
111 0010	114	57	_	_	-	-58.1	72.1	
111 0011	115	_	_	_	_	-54.6	75.5	
111 0100	116	58	29	-	-	-50	79	
111 0101	117	_	_	_	-	-46.5	82.6	
111 0110	118	59	_	_	-	-43	84.9	
111 0111	119	_	-	-	-	-38.3	87.2	
111 1000	120	60	30	15	-	-34.9	89.5	
111 1001	121	-	_	-	-	-31.4	91.8	
111 1010	122	61	_	_	_	-26.7	93	
111 1011	123	- 60	- 21	_	_	-22.1	94.1	
111 1100 111 1101	124 125	62 -	31 -	_		-17.4 -12.7	95.3	
111 1110	125	63		_		-12.7 -8.1	96.5 97.7	
111 1111	127	-		<u> </u>		-8.1 -3.5	98.8	

#### Direction

The direction of rotation is selected by means of following combination of the DIR input pin and the SPI-controlled direction bit <DIRCTRL>. (see Table 15 SPI Control Parameter Overview)

## **NXT** input

Changes on the NXT input will move the motor current one step up/down in the translator table (even when the motor is disabled). Depending on the NXT-polarity bit <NXTP> (see Table 15 SPI Control Parameter Overview), the next step is initiated either on the rising edge or the falling edge of the NXT input.

#### **Translator Position**

The translator position MSP[6:0] can be read in SPI Status Register 3 (See Table 18 SPI Status Registers). This is a 7-bit number equivalent to the 1/32<sup>th</sup> micro-step from Table 12 "Circular Translator Table". The translator position is updated immediately following a NXT trigger.

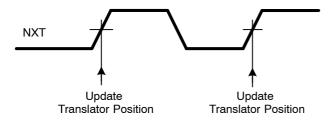


Figure 17. Translator Position Timing Diagram

#### Synchronization of Step Mode and NXT Input

When step mode is re-programmed to another resolution (Figure 18), then this is put in effect immediately upon the first arriving "NXT" input. If the micro-stepping resolution is increased, the coil currents will be regulated to the nearest micro-step, according to the fixed grid of the increased resolution. If however the micro-stepping resolution is decreased, then it is possible to introduce an offset (or phase shift) in the micro-step translator table.

If the step resolution is decreased at a translator table position that is shared both by the old and new resolution setting, then the offset is zero and micro-stepping is proceeds according to the translator table.

If the translator position is <u>not</u> shared both by the old and new resolution setting, then the micro-stepping proceeds with an offset relative to the translator table (See Figure 18 right hand side).

More information can be found in application note AND8399/D.

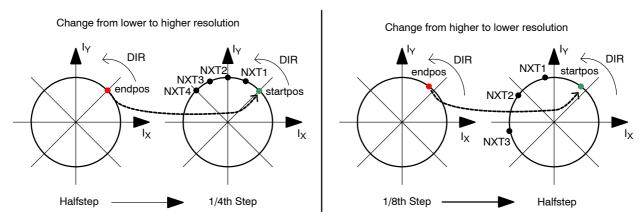


Figure 18. NXT-Step-Mode Synchronization

Left: change from lower to higher resolution. The left-hand side depicts the ending half-step position during which a new step mode resolution was programmed. The right-hand side diagram shows the effect of subsequent NXT commands on the micro-step position.

Right: change from higher to lower resolution. The left–hand side depicts the ending micro–step position during which a new step mode resolution was programmed. The right–hand side diagram shows the effect of subsequent NXT commands on the half–step position.

NOTE: It is advised to reduce the micro-stepping resolution only at micro-step positions that overlap with desired micro-step positions of the new resolution.

#### **Programmable Peak-Current**

The amplitude of the current waveform in the motor coils (coil peak current =  $I_{max}$ ) is adjusted by means of an SPI parameter "CUR[4:0]" (see Table 15 SPI Control Parameter

Overview). Whenever this parameter is changed, the coil-currents will be updated immediately at the next PWM period. Figure 19 presents the Peak-Current and Current Ratings in conjunction to the Current setting CUR[4:0].

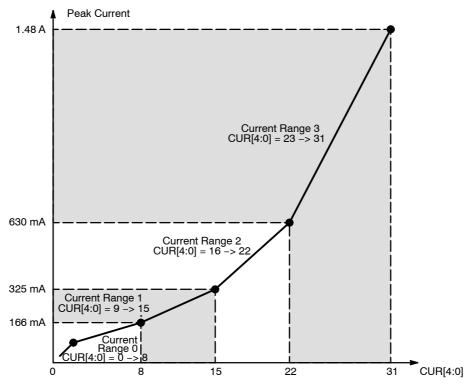


Figure 19. Programmable Peak-Current Overview

## **Speed and Load Angle Output**

The SLA-pin provides an output voltage that indicates the level of the Back-e.m.f. voltage of the motor. This Back-e.m.f. voltage is sampled during every so-called "coil

current zero crossings". Per coil, two zero-current positions exist per electrical period, yielding in total four zero-current observation points per electrical period.

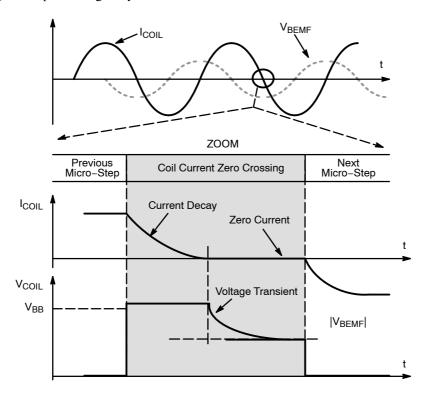


Figure 20. Principle of Bemf Measurement

Because of the relatively high recirculation currents in the coil during current decay, the coil voltage  $V_{\rm COIL}$  shows a transient behavior. As this transient is not always desired in application software, two operating modes can be selected by means of the bit  $\langle {\rm SLAT} \rangle$  (see "SLA-transparency" in Table 15 SPI Control Parameter Overview). The SLA pin shows in "transparent mode" full visibility of the voltage transient behavior. This allows a sanity-check of the speed–setting versus motor operation and characteristics and supply voltage levels. If the bit "SLAT" is cleared, then only the voltage samples at the end of each coil current zero crossing are visible on the SLA-pin. Because the transient behavior of the coil voltage is not visible anymore, this mode

generates smoother Back e.m.f. input for post-processing, e.g. by software.

In order to bring the sampled Back e.m.f. to a descent output level (0 to 5 V), the sampled coil voltage V<sub>COIL</sub> is divided by 2 or by 4. This divider is set through an SPI bit <SLAG> (see Table 15 SPI Control Parameter Overview).

The following drawing illustrates the operation of the SLA-pin and the transparency-bit. "PWMsh" and " $I_{coil} = 0$ " are internal signals that define together with SLAT the sampling and hold moments of the coil voltage.

More information can be found in application note AND8399/D.

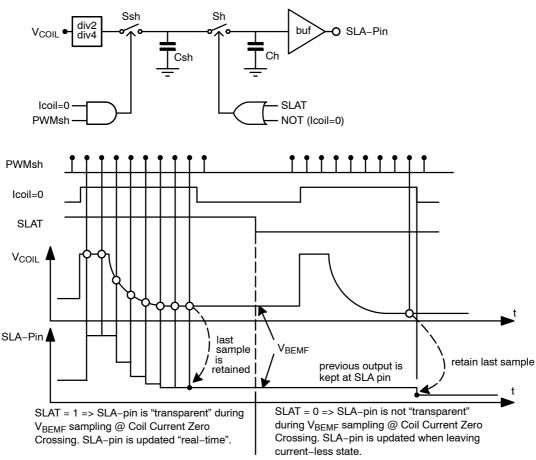


Figure 21. Timing Diagram of SLA-Pin

## Warning, Error Detection and Diagnostics Feedback

#### **Thermal Warning and Shutdown**

When junction temperature rises above  $T_{TW}$ , the thermal warning bit <TW> is set (Table 17 SPI Status registers Address SR0). If junction temperature increases above thermal shutdown level, then the circuit goes in "Thermal Shutdown" mode (<TSD>) and all driver transistors are disabled (high impedance) (see Table 17 SPI Status registers Address SR2). The conditions to reset flag <TSD> is to be at a temperature lower than  $T_{TW}$  and to clear the <TSD> flag reading out Status Register 2.

## Over-Current Detection

The over-current detection circuit monitors the load current in each activated output stage. If the load current exceeds the over-current detection threshold, then the over-current flag is set and the drivers are switched off to reduce the power dissipation and to protect the integrated circuit. Each driver transistor has an individual detection bit in (see Table 17 SPI Status registers Address SR1 and SR2: <ovcint and <ovcint and <ovcint and status bits (by reading Status Register 1 or 2) to reactivate the drivers.

**Note**: Successive reading the SPI StatusRegisters 1 and 2 in case of a short circuit condition, may lead to damage to the drivers

#### **Open Coil/Current Not Reached Detection**

Open coil detection is based on the observation of 100% duty cycle of the PWM regulator. If in a coil 100% duty cycle is detected for longer than 200 ms then the related driver transistors are disabled (high-impedance) and an appropriate bit in the SPI status register is set (<OPENX> or <OPENY>). (Table 17 SPI Status Register Address SR0)

When the resistance of a motor coil is very large and the supply voltage is low, it can happen that the motor driver is not able to deliver the requested current to the motor. Under these conditions the PWM controller duty cycle will be 100% and after 200 ms the error pin and <OPENX>, <OPENY> will flag this situation (motor current is kept alive). This feature can be used to test if the operating conditions (supply voltage, motor coil resistance) still allow reaching the requested coil–current or else the coil current should be reduced.

#### **Charge Pump Failure**

The charge pump is an important circuit that guarantees low  $R_{DS(on)}$  for all drivers, especially for low supply voltages. If supply voltage is too low or external components are not properly connected to guarantee  $R_{DS(on)}$  of the drivers, then the bit <CPFAIL> is set in Table 17. Also after POR the charge pump voltage will need some time to exceed

the required threshold. During that time  $t_{CPU}$  <CPFAIL> will be set to "1".

## **Error Output**

This is a digital output to flag a problem to the external microcontroller. The signal on this output is active low and the logic combination of:

NOT(ERRB) = <TW> OR <TSD> OR <OVCXij> OR < OVCXij> OR <OVCXij> OR <CPFAIL>

This open drain output can be wired OR-ed with error outputs other motor drivers.

## **Logic Supply Regulator**

AMIS-30523 has an on-chip 5 V low-drop regulator with external capacitor to supply the digital part of the chip, some low-voltage analog blocks and external circuitry. The voltage level is derived from an internal bandgap reference. To calculate the available drive-current for external circuitry, the specified I<sub>load</sub> should be reduced with the consumption of internal circuitry (unloaded outputs) and the loads connected to logic outputs. See Table 5 DC parameters Motor Driver.

#### Power-On Reset (POR) Function

The open drain output pin PORB/WD provides an "active low" reset for external purposes. At power-up of AMIS-30523, this pin will be kept low for some time to reset for example an external microcontroller. A small analogue filter avoids resetting due to spikes or noise on the  $V_{DD}$  supply.

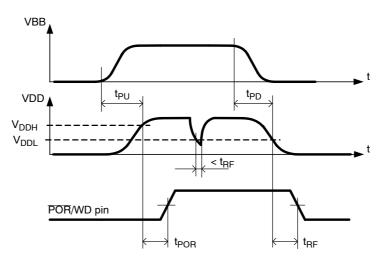


Figure 22. Power-on-Reset Timing Diagram